

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6415xxxxER-G
Typical Mass: 6 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|---------------|------------|------------|
| Silicon chip | 0.399 | Silicon | 66500 | 7440-21-3 |
| | - | Arsenic | 4 | 7440-38-2 |
| Lead pad | 1.100 | Nickel | 183400 | 7440-02-0 |
| | 0.087 | Silver | 14600 | 7440-22-4 |
| | 0.016 | Gold | 2700 | 7440-57-5 |
| Die attach | 0.020 | Epoxy Resin | 3400 | — |
| | 0.016 | Silica | 2600 | 60676-86-0 |
| Bonding wire | 0.045 | Gold | 7600 | 7440-57-5 |
| | | | | |
| Resin | 3.884 | Silica | 647400 | 60676-86-0 |
| | 0.237 | Epoxy Resin | 39600 | — |
| | 0.194 | Phenol Resin | 32400 | — |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."